

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Towle et al.) I hereby certify that this paper is
Serial No.: 10/664,475	being deposited with the UnitedStates Postal Service with
Serial 140 10/004,473) sufficient postage as first class
Filed: September 17, 2003) mail in an envelope addressed to:
•) Commissioner for Patents, P.O.
Assignee: Intel Corporation) Box 1450, Alexandria, VA 22313-
) 1450 on this date:
For: METHODS AND APPARATUS TO)
OPTICALLY COUPLE AN) January 14, 2004
OPTOELECTRONIC CHIP TO A	
WAVEGUIDE) fam (/ lylet
) James A. Flight
Group Art Unit: 2811) /Registration No. 37,622
) Attorney for Applicants
Examiner: Unknown	

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir or Madam:

The patents and/or publications listed on the enclosed PTO Form-1449 are submitted pursuant to 37 CFR §§ 1.56, 1.97, and 1.98. Copies of the patents or publications are enclosed.

TIME OF FILING

This information disclosure statement is being filed to the best of the undersigned's knowledge, before the mailing date of a first Office action on the merits. In accordance with 37 CFR §1.97(b), no certification or fee is required.



PRIOR AND RELATED APPLICATIONS

The examiner is respectfully made aware of the following co-pending application which contains subject matter related to this application:

Applicant(s):

Towle et al.

Serial No.

10/649,240

Filing Date:

August 27, 2003

Title:

OPTOELECTRONIC PACKAGES AND

METHODS TO SIMULTANEOUSLY COUPLE

AN OPTOELECTRONIC CHIP TO A WAVEGUIDE AND SUBSTRATE

Status:

Pending

METHOD OF PAYMENT

No fee is required.

The Commissioner is authorized to charge any fee deficiency required by this paper, or credit any overpayment, to Deposit Account No. 50-2455. A copy of this paper is enclosed.

Correspondence Address:

Respectfully submitted,

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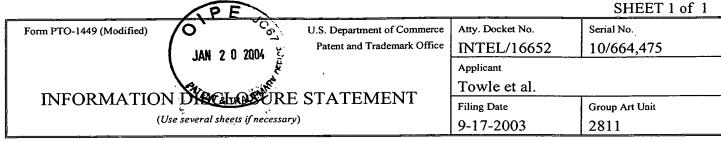
By:

James A. Flight

Registration No.: 37,622

January 14, 2004

Attorneys for Intel Corporation



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*EXAMINER INITIALS	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

		FOREIGN PA	TENT DOCUM	1ENTS			
*Examiner Initials	Document Number	Publication Date	Country	Class	Subclass	Transla Yes	tion No
•							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)
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Bogaerts, W; Bienstman, P; Baets, R. "Sidewall Roughness in Photonic Crystal Slabs: A Comparison of High-Contrast Membranes and Low-Contrast III-V Epitaxial Structures." 11 th International Workshop on Optical Waveguide Theory and Numerical Modelling, April 4-5, 2003, Prague, Czech Republic. Pages 1-4.
"Polymer Technology Overview." Optical Crosslinks, Incorporated. 2001. Pages 1-10. Retrieved from internet: <url: <a="" href="http://www.opticalcrosslinks.com/pdf/WebPolymerTECHNOLOGYPlatform.pdf">http://www.opticalcrosslinks.com/pdf/WebPolymerTECHNOLOGYPlatform.pdf >.</url:>
"Polymer Technology: Performance Data and Design Considerations." Optical Crosslinks, Incorporated. 2001. Pages 1-9. Retrieved from internet: <url: <a="" href="http://www.opticalcrosslinks.com/pdf/WebPerformanceDataDesignTECHNOLGY.pdf">http://www.opticalcrosslinks.com/pdf/WebPerformanceDataDesignTECHNOLGY.pdf>.</url:>

EXAMINER

DATE CONSIDERED